

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BTS50025-1TAD	**Issued**	15. May 2021
MA#	MA004091368		
Package	PG-TO263-7-10	**Weight***	1556.52 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	6.524	0.42	0.42	4191	4191
chip_2	inorganic material	silicon	7440-21-3	1.848	0.12	0.12	1187	1187
leadframe	inorganic material	phosphorus	7723-14-0	0.247	0.02		159	
	non noble metal	iron	7439-89-6	0.823	0.05		529	
	non noble metal	copper	7440-50-8	822.375	52.84	52.91	528342	529030
wire	non noble metal	aluminium	7429-90-5	12.040	0.77	0.77	7735	7735
encapsulation	inorganic material	zincoxide	1314-13-2	5.620	0.36		3610	
	miscellaneous	miscellaneous	-	22.478	1.44		14441	
	plastics	epoxy resin	-	84.294	5.42		54155	
	inorganic material	silicondioxide	60676-86-0	449.567	28.88	36.10	288828	361034
leadfinish	non noble metal	tin	7440-31-5	12.163	0.78	0.78	7814	7814
plating	inorganic material	phosphorus	7723-14-0	0.007			5	
	non noble metal	nickel	7440-02-0	2.941	0.19	0.19	1889	1894
solder	non noble metal	tin	7440-31-5	0.093	0.01		60	
	noble metal	silver	7440-22-4	0.116	0.01		75	
	non noble metal	lead	7439-92-1	4.430	0.28	0.30	2846	2981
glue	plastics	Polyimide	26023-21-2	0.198	0.01	0.01	127	127
heatspreader	inorganic material	phosphorus	7723-14-0	0.039			25	
	non noble metal	iron	7439-89-6	0.131	0.01		84	
	non noble metal	copper	7440-50-8	130.589	8.39	8.40	83898	84007
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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